

# 1.7x0.6 x1.1mm Side View Chip LED

# OSXX0602C1E

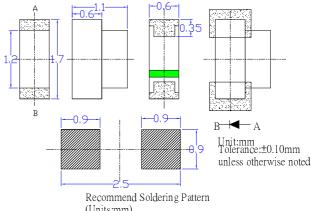
#### **■Features**

- Single chip
- Super high brightness of surface mount LED
- Compact package outline (L x W x T) of 1.7mm x 0.6mm x1.1mm
- Compatible to IR reflow soldering.
- Water clear type.(Except White & Warm White)

# Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

#### **■Outline Dimension**



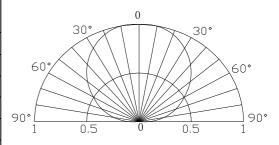
(Units:mm)

# ■Absolute Maximum Rating

# (Ta=25°C)

#### Value Item Symbol Unit G8/Y5/O5/R5 WA/M5/B5/G5 DC Forward Current 20 20 $I_F$ mA Pulse Forward Current# 100 80 $I_{FP}$ mA Reverse Voltage $V_R$ 5 5 V 66 Power Dissipation $P_{\rm D}$ 46 mW Operating Temperature Topr -40 ~ +85 $^{\circ}$ C $^{\circ}$ C Storage Temperature -40~ +85 Tstg Lead Soldering Temperature 260°C/10sec Tsol

# Directivity



#Pulse width Max 0.1ms, Duty ratio max 1/10

# **■**Electrical -Optical Characteristics

# (Ta=25°C)

				V <sub>F</sub> (V)			$I_R(\mu A)$	Iv(mcd)		λD(nm)			θ1/2(deg)	
Part Number Color			Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	
				I <sub>F</sub> =5mA			V <sub>R</sub> =5V	I <sub>F</sub> =5mA						
OSWA0602C1E	White	WA		-	2.7	3.3	10	100	150	-	6000K	8500K	12500K	120
OSM50602C1E	Warm White	M5		-	2.7	3.3	10	100	150	-	2900K	3100K	3300K	120
OSB50602C1E	Blue	В5		-	2.7	3.3	10	35	70	-	460	465	475	120
OSG50602C1E	True Green	G5		-	2.7	3.3	10	120	180	-	515	523	530	120
OSG80602C1E	Yellow Green	G8		-	1.7	2.3	10	8	15	-	565	570	575	120
OSY50602C1E	Yellow	Y5		-	1.7	2.3	10	20	45	-	585	590	595	120
OSO50602C1E	Orange	O5		-	1.7	2.3	10	20	45	-	600	605	610	120
OSR50602C1E	Red	R5		-	1.7	2.3	10	20	45	-	615	620	630	120

<sup>\*1</sup> Tolerance of measurements of chromaticity coordinate is +10%

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<sup>\*2</sup> Tolerance of measurements of dominant wavelength is +1nm

<sup>\*3</sup> Tolerance of measurements of luminous intensity is ±15%

<sup>\*4</sup> Tolerance of measurements of forward voltage is±0.1V



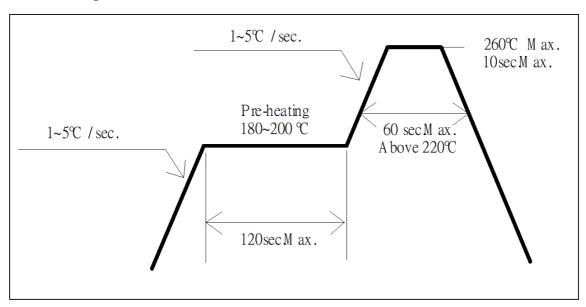
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### **■** Soldering Conditions

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ∼ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak temperature	260°C Max.	Temperature	350°C Max.		
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.		
Condition	Refer to Temperature-profile		(one time only)		

# • Reflow Soldering Condition(Lead-free Solder)



- \*Recommended soldering conditions vary according to the type of LED
- \*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- \*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.







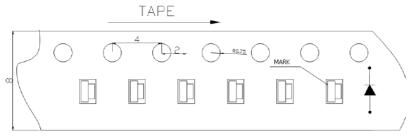




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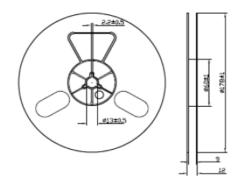
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### ■ PACKING



Package: 4000PCS/reel

#### **■Reel Dimensions**



Note: The tolerances unless mentioned is ±0.1mm,Unit:mm

#### **■ Cautions:**

- 1. After open the package, the LED's floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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